

20V N-Channel Enhancement Mode MOSFET

Description

The PECN2020SR uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

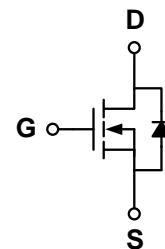
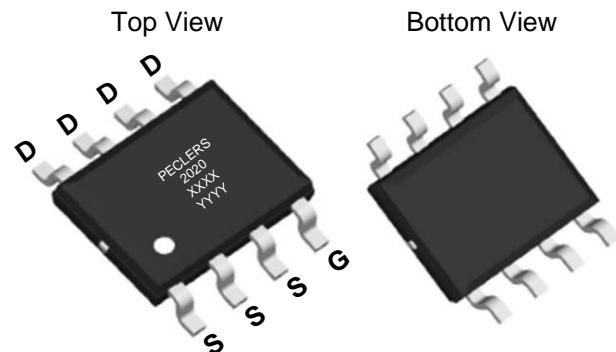
- ◆ $V_{DS} = 20V \quad I_D = 20A$
 $R_{DS(ON)}(\text{Typ.}) = 4.7m\Omega \quad @ V_{GS} = 4.5V$
 $R_{DS(ON)}(\text{Typ.}) = 5.1m\Omega \quad @ V_{GS} = 2.5V$
 $R_{DS(ON)}(\text{Typ.}) = 6.8m\Omega \quad @ V_{GS} = 1.8V$
- ◆ High density cell design for ultra low $R_{DS(on)}$
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation
- ◆ Special process technology for high ESD capability
- ◆ 100% UIS tested

Application

- ◆ Automotive applications
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply

Package*100% UIS TESTED!*

- ◆ SOP-8

*100% ΔV_{ds} TESTED!***Schematic diagram****Marking and pin assignment****SOP-8**

PECLERS 2020—Product Name

XXXX—Wafer Lot No.

YYYY—Date Code

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN2020SR	-55°C to +150°C	SOP-8	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	20	V
Gate-source voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	20	A
		16	
Pulsed Drain Current	I_{DP}	140	A
Avalanche energy(L=0.5mH) ^(note1)	E_{AS}	160	mJ
Maximum power dissipation	P_D	3.1	W
		2	

Operating junction Temperature range	T _j	-55—150	°C
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Thermal Characteristics

Parameter		Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	≤ 10s	$R_{\theta JA}$	33	40	°C/W
Maximum Junction-to-Ambient ^A	Steady-State		59	75	
Maximum Junction-to-Lead ^B	Steady-State	$R_{\theta JC}$	16	24	

A:The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10s$ thermal resistance rating.

B: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JC}$ and lead to ambient.

C:Eas test: VDD=10V, RG=25ohm, L=500Uh

D:Pulse test; pulse width $\leq 300ns$, duty cycle $\leq 2\%$.

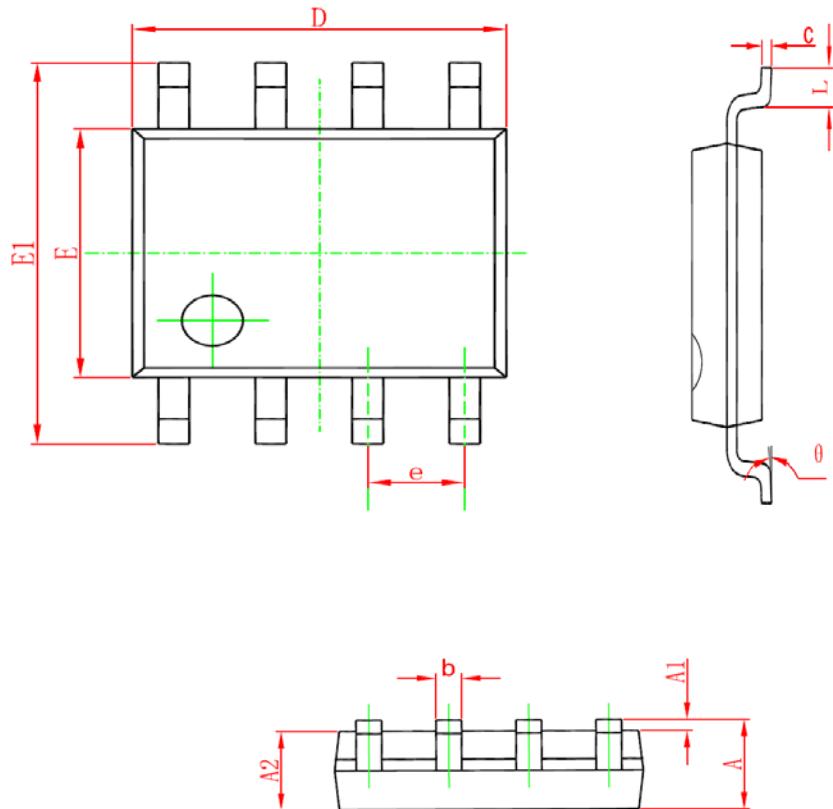
E:Guaranteed by design, not subject to production testing.

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	T _J =25°C	-	-	1
			T _J =85°C	-	-	5
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	1.2	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	4.7	5.5	mΩ
		V _{GS} =2.5V, I _D =10A	-	5.1	7	
		V _{GS} =1.8V, I _D =10A		6.8	9	
On Status Drain Current	I _{D(ON)}	V _{DS} =20V, V _{GS} =4.5V	40	-	-	A
Diode Characteristics						
Diode Continuous Forward Current	I _S		-	-	12	A
Reverse Recovery Time	t _{rr}	I _F =10A, dI/dt=20A/us	-	25	-	ns
Reverse Recovery Charge	Q _{rr}		-	24	-	nC
Dynamic Characteristics²						
Input capacitance	C _{ISS}	V _{GS} =0V , V _{DS} =10V f=1.0MHz	-	2000	-	pF
Output capacitance	C _{OSS}		-	500	-	
Reverse transfer capacitance	C _{RSS}		-	200	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =4.5V, V _{DD} =10V, I _D =2A	-	6.5	-	ns
Turn-on Rise time	t _r		-	17	-	
Turn-off delay time	t _{D(OFF)}		-	29.5	-	
Turn-off Fall time	t _f		-	17	-	
Total gate charge	Q _g	V _{GS} =4.5V,I _D =10A V _{DS} =10V	-	27	-	nC
Gate-source charge	Q _{gs}			6.5	-	
Gate-drain charge	Q _{gd}		-	6.4	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V _{SD}	I _{SD} =10A,V _{GS} =0V	-	0.8	1.2	V

Package Information

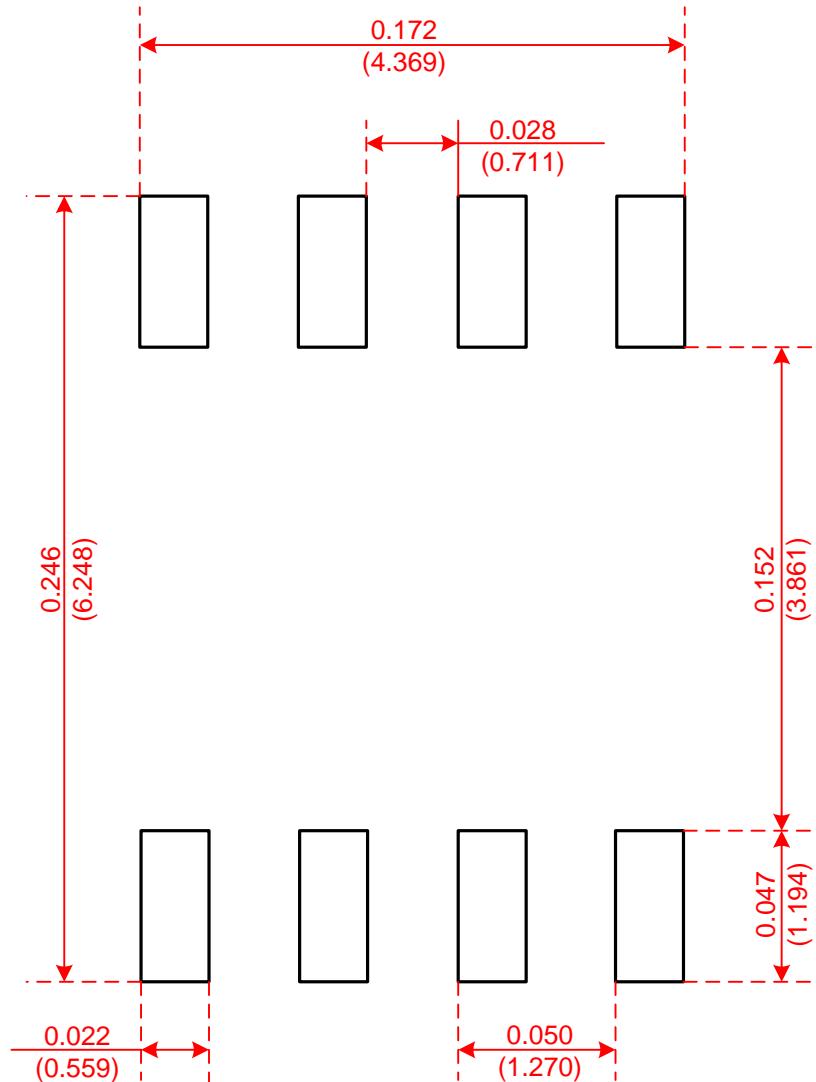
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Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Recommended Minimum Pads

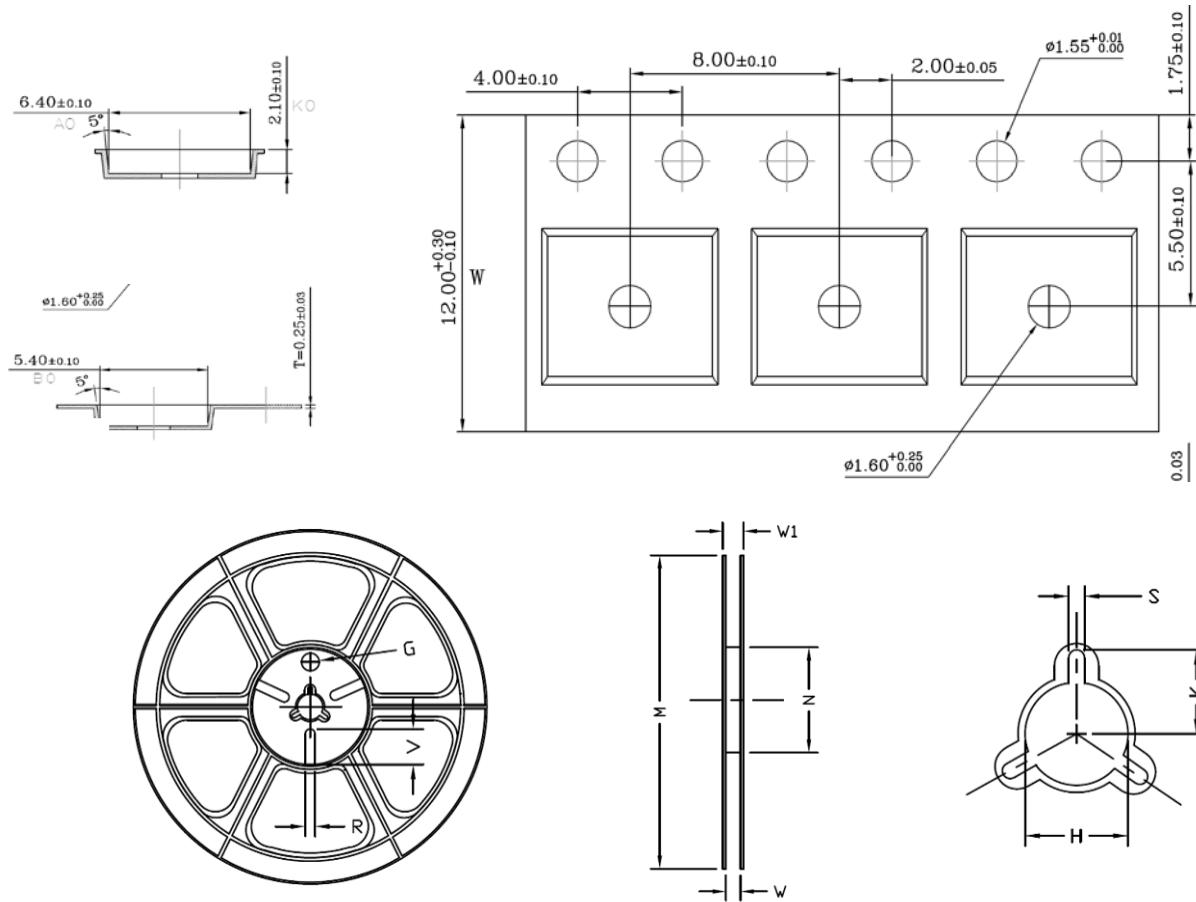
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Recommended Minimum Pads
Dimensions in Inches/(mm)

Tape and Reel

- SOP-8



Tape Size	Reel Size	M	N	W	W1	H	K	S	G	R	V
12mm	$\phi 330$	$\phi 330.00 \pm 0.50$	$\phi 97.00 \pm 0.30$	13.00 ± 0.30	17.40 ± 1.00	$\phi 13.00 \pm 0.5$	10.6	2.00 ± 0.50	—	—	—

